



(1MB) 4x64Kx32 Synchronous SRAM CARD EDGE DIMM

FEATURES

- 4x64Kx32 Synchronous
- Access Speed(s): $T_{KHQV} = 9.5, 10, 11, 12, 15\text{ns}$
- Flow-Through Architecture
- Clock Controlled Registered Bank Enables (E1\, E2\, E3, E4\)
- Clock Controlled Registered Address
- Clock Controlled Registered Global Write (GW\)
- Asynchronous Output Enable (G\)
- Internally self-timed Write
- Gold Lead Finish
- 3.3V +10%, -5% Operation
- Common Data I/O
- High Capacitance (30pF) drive, at rated Access Speed
- Single total array Clock
- Multiple Vcc and Vss

The EDI2GG43264VxD is a Synchronous SRAM, 60 position, Card Edge DIMM (120 contacts) Module, organized as 4x64Kx32. The Module contains four (4) Synchronous Burst Ram Devices, packaged in the industry standard JEDEC 14mmx20mm TQFP placed on a Multilayer FR4 Substrate. The module architecture is defined as a Synchronous Only, Flow-Through, Early Write Device. This Module provides high performance, ultra fast access times at a cost per bit benefit over BiCMOS Asynchronous SRAM based devices. As well as improved cost per bit, the use of Synchronous or Synchronous Burst Devices or Modules can ease the memory subsystem design by reducing or easing the memory controller requirement.

Synchronous operations are in relation to an externally supplied clock, registered address, registered global write, registered enables as well as an Asynchronous Output enable. All read and write operations to this module are performed on long words (double words) 32 bit operations.

Write cycles are internally self timed and are initiated by a rising clock edge. This feature relieves the designer the task of developing external write pulse width circuitry.

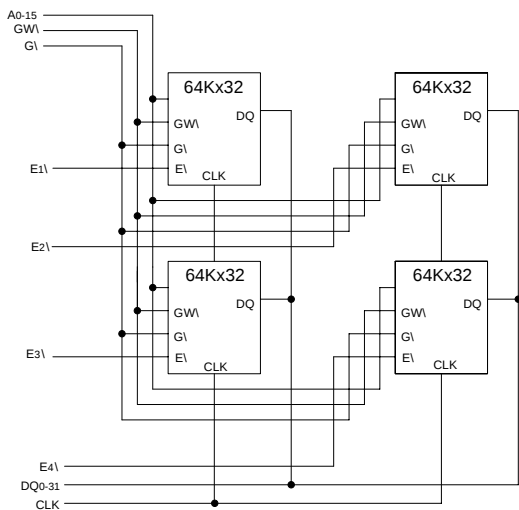


PIN CONFIGURATION

VSS	1	2	VSS
A0	3	4	NC
A1	5	6	A15
A2	7	8	A14
A3	9	10	A13
VCC	11	12	VCC
A4	13	14	A12
A5	15	16	A11
A6	17	18	A10
A7	19	20	A9
VSS	21	22	VSS
A8	23	24	RFU
VSS	25	26	VSS
CLK	27	28	ZZ
VSS	29	30	VSS
E4\	31	32	E2\
VCC	33	34	VCC
E3\	35	36	E1\
G\	37	38	GW\
VSS	39	40	VSS
DQ0	41	42	DQ7
DQ1	43	44	DQ6
DQ2	45	46	DQ5
DQ3	47	48	DQ4
VCC	49	50	VCC
DQ8	51	52	DQ15
DQ9	53	54	DQ14
DQ10	55	56	DQ13
DQ11	57	58	DQ12
VSS	59	60	VSS
DQ16	61	62	DQ23
DQ17	63	64	DQ22
DQ18	65	66	DQ21
DQ19	67	68	DQ20
VCC	69	70	VCC
DQ24	71	72	DQ31
DQ26	73	74	DQ30
DQ25	75	76	DQ29
DQ27	77	78	DQ28
VSS	79	80	VSS
NC	81	82	NC
NC	83	84	NC
NC	85	86	NC
NC	87	88	NC
VCC	89	90	VCC
NC	91	92	NC
NC	93	94	NC
NC	95	96	NC
NC	97	98	NC
VSS	99	100	VSS
NC	101	102	NC
NC	103	104	NC
NC	105	106	NC
NC	107	108	NC
VCC	109	110	VCC
NC	111	112	NC
NC	113	114	NC
NC	115	116	NC
NC	117	118	NC
VSS	119	120	VSS



FUNCTIONAL BLOCK DIAGRAM



PIN NAMES

DQ0-32	Input/Output Bus
A0-15	Address Bus
E1-4	Synchronous Bank Enables
CLK	Array Clock
GW	Synchronous Global Write Enable
G	Asynchronous Output Enable
Vcc	3.3V Power Supply
Vss	Ground
NC	No Connect

PIN DESCRIPTIONS

DIMM Pins	Symbol	Type	Description
3, 5, 7, 9, 13, 15, 17, 19, 20, 23, 18, 16, 14, 10, 8, 6	A0-15	Input Synchronous	Addresses: These inputs are registered and must meet the setup and hold times around the rising edge of CLK. The burst counter generates internal addresses associated with A0 and A1, during burst and wait cycle.
38	GW	Input Synchronous	Global Write: This active LOW input allows a full 72-bit WRITE to occur independent of the BWE and BW lines and must meet the setup and hold times around the rising edge of CLK.
27	CLK	Input Synchronous	Clock: This signal registers the addresses, data, chip enables, write control and burst control inputs on its rising edge. All synchronous inputs must meet setup and hold times around the clock's rising edge.
36, 32, 35, 31	E1, E2, E3, E4	Input Synchronous	Bank Enables: These active LOW inputs are used to enable each individual bank and to gate ADSP.
37	G	Input	Output Enable: This active LOW asynchronous input enables the data output drivers.
Various	DQ0-32	Input/Output	Data Inputs/Outputs: First byte is DQ0-7, second byte is DQ8-15, third byte is DQ16-23, fourth byte is DQ24-31, fifth byte is DQ32-39, sixth byte is DQ40-47, seventh byte is DQ48-55 and the eighth byte is DQ56-64.
Various	Vcc	Supply	Core power supply: +3.3V -5%/+10%
Various	Vss	Ground	Ground


SYNCHRONOUS ONLY - TRUTH TABLE

Operation	E1\	E2\	E3\	E4\	GW\	G\	CLK	DQ
Synchronous Write-Bank 1	L	H	H	H	L	H	↑	High-Z
Synchronous Read-Bank 1	L	H	H	H	H	L	↑	
Synchronous Write-Bank 2	H	L	H	H	L	H	↑	High-Z
Synchronous Read-Bank 2	H	L	H	H	H	L	↑	
Synchronous Write-Bank 3	H	H	L	H	L	H	↑	High-Z
Synchronous Read-Bank 3	H	H	L	H	H	L	↑	
Synchronous Write-Bank 4	H	H	H	L	L	H	↑	High-Z
Synchronous Read-Bank 4	H	H	H	L	H	L	↑	
Snooze Mode	X	X	X	X	X	X	X	High-Z

ABSOLUTE MAXIMUM RATINGS*

Voltage on Vcc Relative to Vss	-0.5V to +4.6V
Vin	-0.5V to Vcc +0.5V
Storage Temperature	-55°C to +125°C
Operating Temperature (Commercial)	0°C to +70°C
Operating Temperature (Industrial)	-40°C to +85°C
Short Circuit Output Current	20 mA

*Stress greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions greater than those indicated in operational sections of this specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

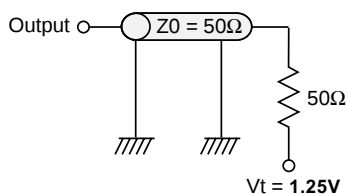
RECOMMENDED DC OPERATING CONDITIONS

Parameter	Sym	Min	Typ	Max	Units
Supply Voltage	Vcc	3.14	3.3	3.6	V
Supply Voltage	Vss	0.0	0.0	0.0	V
Input High	VIH	2.2	3.0	Vcc +0.3	V
Input Low	VIL	-0.3	0.0	0.8	V
Input Leakage	ILI	-2	1	2	μA
Output Leakage	ILO	-2	1	2	μA
Output High (IOH = -4mA)	VOH	2.4	-	-	V
Output Low (IOL = 8mA)	VOL	-	-	0.4	V

DC ELECTRICAL CHARACTERISTICS - READ CYCLE

Description	Symbol	Typ	9.5	10	Max 11	12	15	Units
Power Supply Current	Icc1	195	*	480	480	420	385	mA
Power Supply Current Device Selected, No Operation	Icc	80	*	300	300	270	270	mA
Snooze Mode	Icczz	4	*	20	20	20	20	mA
CMOS Standby	Icc3	60	*	100	100	100	100	mA
Clock Running-Deselect	Icck	80	*	3000	300	270	270	mA

*TBD

AC TEST CIRCUIT


AC Output Load Equivalent

AC TEST CONDITIONS

Parameter	I/O	Unit
Input Pulse Levels	Vss to 3.0	V
Input and Output Timing Levels	1.25	V
Output Test Equivalencies	See figure, at left	


READ CYCLE TIMING PARAMETERS

Description	Sym	9.5ns		10ns		11ns		12ns		15ns		Units
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Clock Cycle Time	t _{KHKH}	*	*	12		12		15		20		ns
Clock High Time	t _{KHKL}	*	*	5		5		5		6		ns
Clock Low Time	t _{KLKH}	*	*	5		5		5		6		ns
Clock to Output Valid	t _{KHQV}	*	*		10		11		12		15	ns
Clock to Output Invalid	t _{KHQX1}	*	*	3		3		3		3		ns
Clock to Output Low-Z	t _{KHQX}	*	*	2		2		2		2		ns
Output Enable to Output Valid	t _{GLQV}	*	*		5		5		5		6	ns
Output Enable to Output Low-Z	t _{GLQX}	*	*	0		0		0		0		ns
Output Enable to Output High-Z	t _{GHQZ}	*	*		5		5		5		6	ns
Address Setup	t _{AVKH}	*	*	2.5		2.5		2.5		2.5		ns
Bank Enable Setup	t _{EVKH}	*	*	2.5		2.5		2.5		2.5		ns
Address Hold	t _{KHAX}	*	*	1.0		1.0		1.0		1.0		ns
Bank Enable Hold	t _{KHEX}	*	*	1.0		1.0		1.0		1.0		ns

*TBD

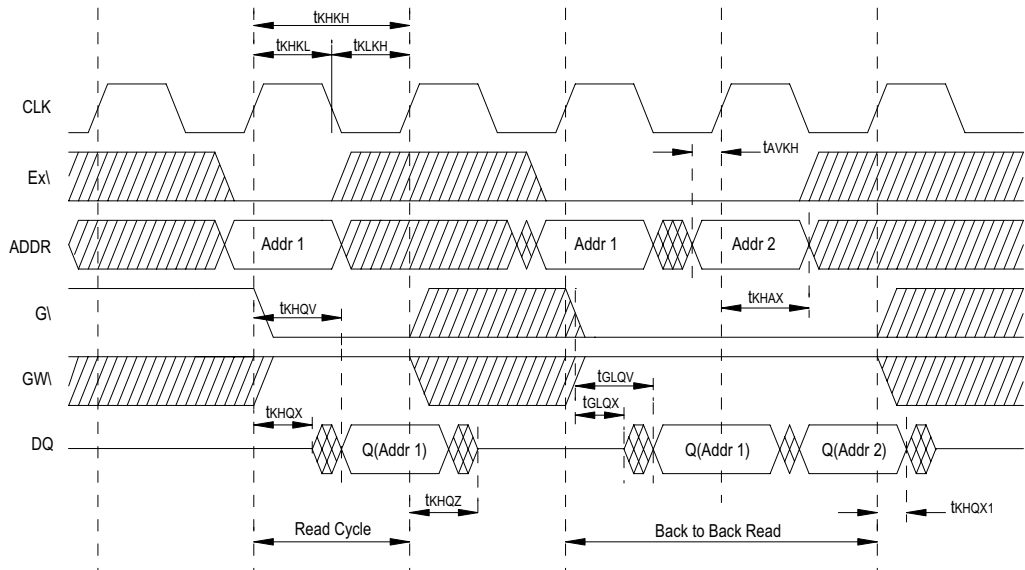
WRITE CYCLE TIMING PARAMETERS

Description	Sym	9.5ns		10ns		11ns		12ns		15ns		Units
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Clock Cycle Time	t _{KHKH}	*	*	12		12		15		20		ns
Clock High Time	t _{KHKL}	*	*	5		5		5		6		ns
Clock Low Time	t _{KLKH}	*	*	5		5		5		6		ns
Address Setup	t _{AVKH}	*	*	2.5		2.5		2.5		2.5		ns
Address Hold	t _{KHAX}	*	*	1.0		1.0		1.0		1.0		ns
Bank Enable Setup	t _{EVKH}	*	*	2.5		2.5		2.5		2.5		ns
Bank Enable Hold	t _{KHEX}	*	*	1.0		1.0		1.0		1.0		ns
Global Write Enable Setup	t _{WVKH}	*	*	2.5		2.5		2.5		2.5		ns
Global Write Enable Hold	t _{KHWX}	*	*	1.0		1.0		1.0		1.0		ns
Data Setup	t _{DVKH}	*	*	2.5		2.5		2.5		2.5		ns
Data Hold	t _{KHDX}	*	*	1.0		1.0		1.0		1.0		ns

*TBD

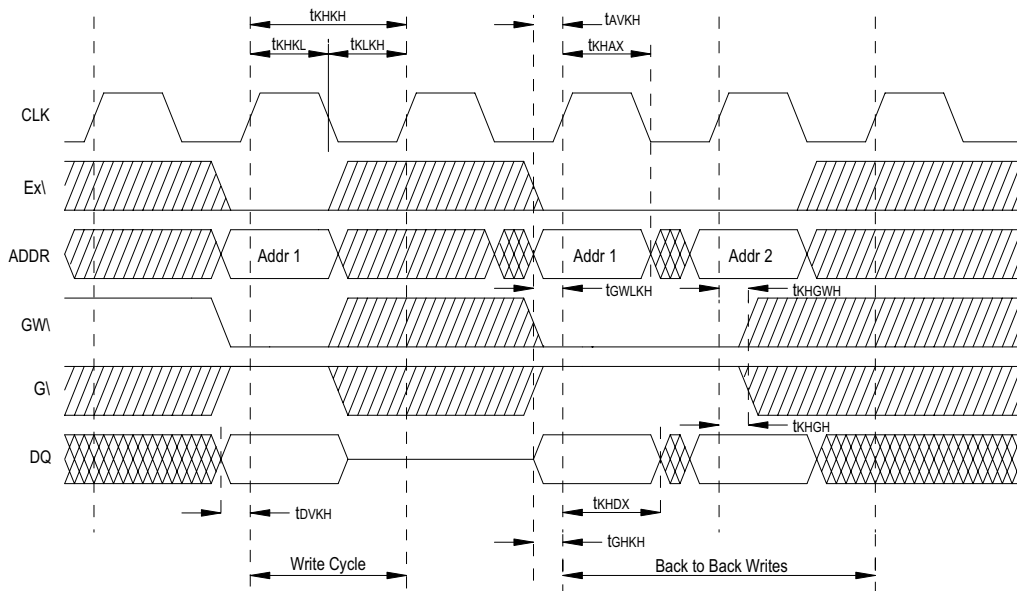


SYNCHRONOUS READ CYCLE

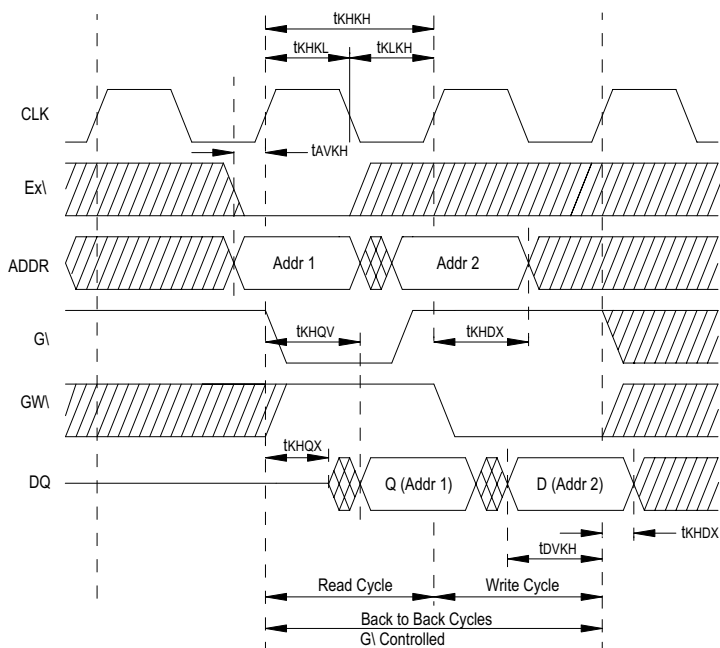




SYNCHRONOUS WRITE CYCLE



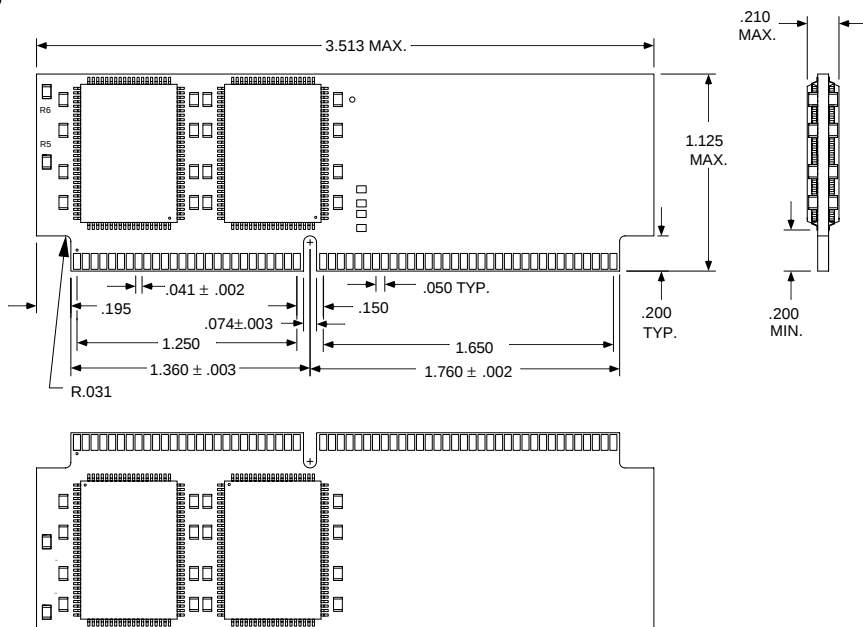
SYNCHRONOUS READ/WRITE CYCLE





PACKAGE DESCRIPTION: 120 LEAD CARD EDGE DIMM

Package No. 413



ALL DIMENSIONS ARE IN INCHES

ORDERING INFORMATION

Part Number	Organization	Voltage	Speed (ns)	Package
EDI2GG43264V95D*	4x64Kx32	3.3	9.5	120 Card Edge DIMM
EDI2GG43264V10D*	4x64Kx32	3.3	10	120 Card Edge DIMM
EDI2GG43264V11D*	4x64Kx32	3.3	11	120 Card Edge DIMM
EDI2GG43264V12D*	4x64Kx32	3.3	12	120 Card Edge DIMM
EDI2GG43264V15D*	4x64Kx32	3.3	15	120 Card Edge DIMM

*Consult Factory for Availability